

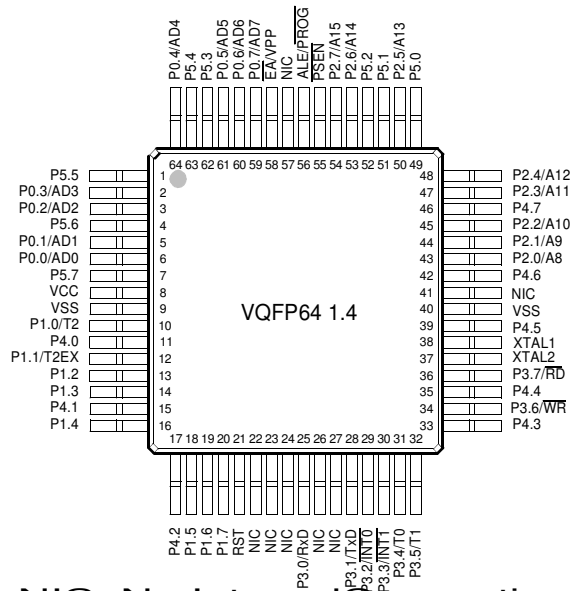
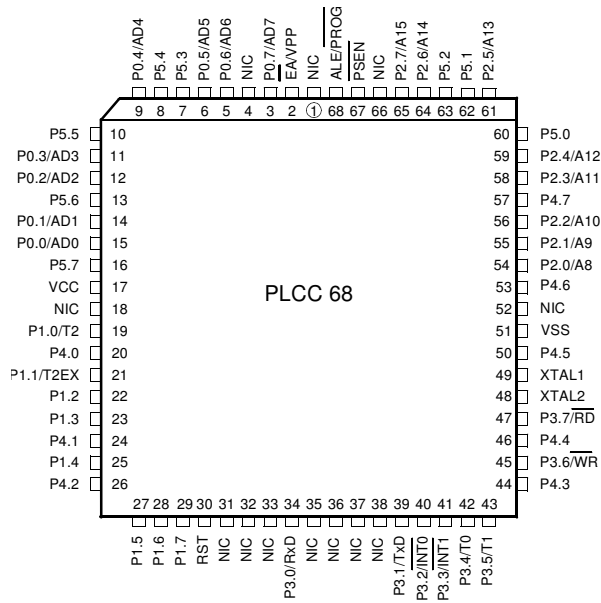
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Details	
Product Status	Active
Core Processor	80C51
Core Size	8-Bit
Speed	40/20MHz
Connectivity	UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	32
Program Memory Size	16KB (16K x 8)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.6x16.6)
Purchase URL	https://www.e-xfl.com/product-detail/atmel/at87c51rb2-slrum



NIC: No Internal Connection

Mnemonic	Pin Number			Type	Name And Function
	DIL	LCC	VQFP 1.4		
	12	14	8	I	$\overline{\text{INT0}}$ (P3.2): External interrupt 0
	13	15	9	I	$\overline{\text{INT1}}$ (P3.3): External interrupt 1
	14	16	10	I	T0 (P3.4): Timer 0 external input
	15	17	11	I	T1 (P3.5): Timer 1 external input
	16	18	12	O	$\overline{\text{WR}}$ (P3.6): External data memory write strobe
	17	19	13	O	$\overline{\text{RD}}$ (P3.7): External data memory read strobe
Reset	9	10	4	I	Reset: A high on this pin for two machine cycles while the oscillator is running, resets the device. An internal diffused resistor to V_{SS} permits a power-on reset using only an external capacitor to V_{CC} . If the hardware watchdog reaches its time-out, the reset pin becomes an output during the time the internal reset is activated.
$\overline{\text{ALE/PROG}}$	30	33	27	O (I)	Address Latch Enable/Program Pulse: Output pulse for latching the low byte of the address during an access to external memory. In normal operation, ALE is emitted at a constant rate of 1/6 (1/3 in X2 mode) the oscillator frequency, and can be used for external timing or clocking. Note that one ALE pulse is skipped during each access to external data memory. This pin is also the program pulse input ($\overline{\text{PROG}}$) during EPROM programming. ALE can be disabled by setting SFR's AUXR.0 bit. With this bit set, ALE will be inactive during internal fetches.
PSEN	29	32	26	O	Program Store Enable: The read strobe to external program memory. When executing code from the external program memory, $\overline{\text{PSEN}}$ is activated twice each machine cycle, except that two $\overline{\text{PSEN}}$ activations are skipped during each access to external data memory. $\overline{\text{PSEN}}$ is not activated during fetches from internal program memory.
$\overline{\text{EA}}/V_{PP}$	31	35	29	I	External Access Enable/Programming Supply Voltage: $\overline{\text{EA}}$ must be externally held low to enable the device to fetch code from external program memory locations 0000H and 3FFFH (RB) or 7FFFH (RC), or FFFFH (RD). If EA is held high, the device executes from internal program memory unless the program counter contains an address greater than 3FFFH (RB) or 7FFFH (RC). $\overline{\text{EA}}$ must be held low for ROMless devices. This pin also receives the 12.75V programming supply voltage (V_{PP}) during EPROM programming. If security level 1 is programmed, $\overline{\text{EA}}$ will be internally latched on Reset.
XTAL1	19	21	15	I	Crystal 1: Input to the inverting oscillator amplifier and input to the internal clock generator circuits.
XTAL2	18	20	14	O	Crystal 2: Output from the inverting oscillator amplifier

5.1 Pin Description for 64/68 pin Packages

Port 4 and Port 5 are 8-bit bidirectional I/O ports with internal pull-ups. Pins that have 1s written to them are pulled high by the internal pull ups and can be used as inputs.

As inputs, pins that are externally pulled low will source current because of the internal pull-ups.

Refer to the previous pin description for other pins.

Table 5-1. 64/68 Pin Packages Configuration

Pin	PLCC68	SQUARE VQFP64 1.4
VSS	51	9/40
VCC	17	8

P0.0	15	6
P0.1	14	5
P0.2	12	3
P0.3	11	2
P0.4	9	64
P0.5	6	61
P0.6	5	60
P0.7	3	59
P1.0	19	10
P1.1	21	12
P1.2	22	13
P1.3	23	14
P1.4	25	16
P1.5	27	18
P1.6	28	19
P1.7	29	20
P2.0	54	43
P2.1	55	44
P2.2	56	45
P2.3	58	47
P2.4	59	48
P2.5	61	50
P2.6	64	53
P2.7	65	54
P3.0	34	25
P3.1	39	28

Pin	PLCC68	SQUARE VQFP64 1.4
P3.2	40	29
P3.3	41	30
P3.4	42	31
P3.5	43	32
P3.6	45	34
P3.7	47	36
RESET	30	21
ALE/ $\overline{\text{PROG}}$	68	56

5.4 Dual Data Pointer Register

The additional data pointer can be used to speed up code execution and reduce code size in a number of ways.

The dual DPTR structure is a way by which the chip will specify the address of an external data memory location. There are two 16-bit DPTR registers that address the external memory, and a single bit called DPS = AUXR1/bit0 (Table 5-3) that allows the program code to switch between them (Refer to Figure 5-3).

Figure 5-3. Use of Dual Pointer

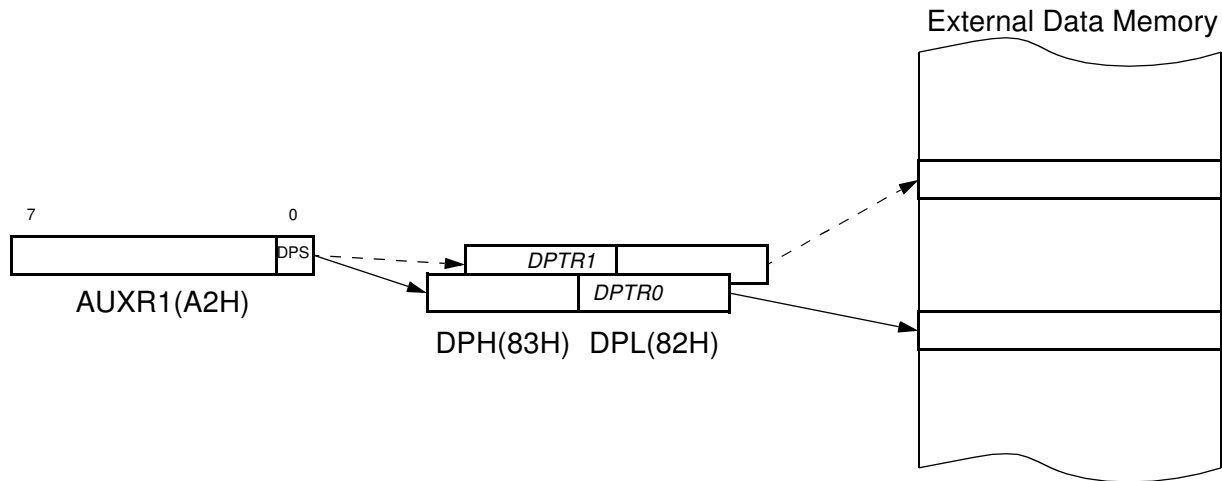


Table 5-3. AUXR1: Auxiliary Register 1

AUXR1 Address 0A2H		-	-	-	-	GF3	-	-	DPS
	Reset value	X	X	X	X	0	X	X	0
Symbol	Function								
-	Not implemented, reserved for future use ⁽¹⁾								
DPS	Data Pointer Selection.								
	DPS	Operating Mode							
	0	DPTR0 Selected							
	1	DPTR1 Selected							
GF3	This bit is a general purpose user flag ⁽²⁾ .								

1. User software should not write 1s to reserved bits. These bits may be used in future 8051 family products to invoke new feature. In that case, the reset value of the new bit will be 0, and its active value will be 1. The value read from a reserved bit is indeterminate.

GF3 will not be available on first version of the RC devices.

6.1 Expanded RAM (XRAM)

The TS80C51Rx2 provide additional Bytes of random access memory (RAM) space for increased data parameter handling and high level language usage.

RA2, RB2 and RC2 devices have 256 bytes of expanded RAM, from 00H to FFH in external data space; RD2 devices have 768 bytes of expanded RAM, from 00H to 2FFH in external data space.

The TS80C51Rx2 has internal data memory that is mapped into four separate segments.

The four segments are:

- 1. The Lower 128 bytes of RAM (addresses 00H to 7FH) are directly and indirectly addressable.
- 2. The Upper 128 bytes of RAM (addresses 80H to FFH) are indirectly addressable only.
- 3. The Special Function Registers, SFRs, (addresses 80H to FFH) are directly addressable only.
- 4. The expanded RAM bytes are indirectly accessed by MOVX instructions, and with the EXTRAM bit cleared in the AUXR register. (See Table 6-1.)

The Lower 128 bytes can be accessed by either direct or indirect addressing. The Upper 128 bytes can be accessed by indirect addressing only. The Upper 128 bytes occupy the same address space as the SFR. That means they have the same address, but are physically separate from SFR space.

When an instruction accesses an internal location above address 7FH, the CPU knows whether the access is to the upper 128 bytes of data RAM or to SFR space by the addressing mode used in the instruction.

- Instructions that use direct addressing access SFR space. **For example: MOV 0A0H, # data**, accesses the SFR at location 0A0H (which is P2).
- Instructions that use indirect addressing access the Upper 128 bytes of data RAM. **For example: MOV @R0, # data** where R0 contains 0A0H, accesses the data byte at address 0A0H, rather than P2 (whose address is 0A0H).
- The 256 or 768 XRAM bytes can be accessed by indirect addressing, with EXTRAM bit cleared and MOVX instructions. This part of memory which is physically located on-chip, logically occupies the first 256 or 768 bytes of external data memory.
- With EXTRAM = 0, the XRAM is indirectly addressed, using the MOVX instruction in combination with any of the registers R0, R1 of the selected bank or DPTR. **An access to XRAM will not affect ports P0, P2, P3.6 (WR) and P3.7 (RD).** **For example, with EXTRAM = 0, MOVX @R0, # data** where R0 contains 0A0H, accesses the XRAM at address 0A0H rather than external memory. An access to external data memory locations higher than FFH (i.e. 0100H to FFFFH) (higher than 2FFH (i.e. 0300H to FFFFH for RD devices) will be performed with the MOVX DPTR instructions in the same way as in the standard 80C51, so with P0 and P2 as data/address busses, and P3.6 and P3.7 as write and read timing signals. Refer to Figure 6-1. For RD devices, accesses to expanded RAM from 100H to 2FFH can only be done thanks to the use of DPTR.
- With EXTRAM = 1, MOVX @Ri and MOVX @DPTR will be similar to the standard 80C51. MOVX @ Ri will provide an eight-bit address multiplexed with data on Port0 and any output port pins can be used to output higher order address bits. This is to provide the external paging capability. MOVX @DPTR will generate a sixteen-bit address. Port2 outputs the high-order eight address bits (the contents of DPH) while Port0 multiplexes the low-order eight

address bits (DPL) with data. MOVX @ Ri and MOVX @DPTR will generate either read or write signals on P3.6 (WR) and P3.7 (RD).

The stack pointer (SP) may be located anywhere in the 256 bytes RAM (lower and upper RAM) internal data memory. The stack may not be located in the XRAM.

Figure 6-1. Internal and External Data Memory Address

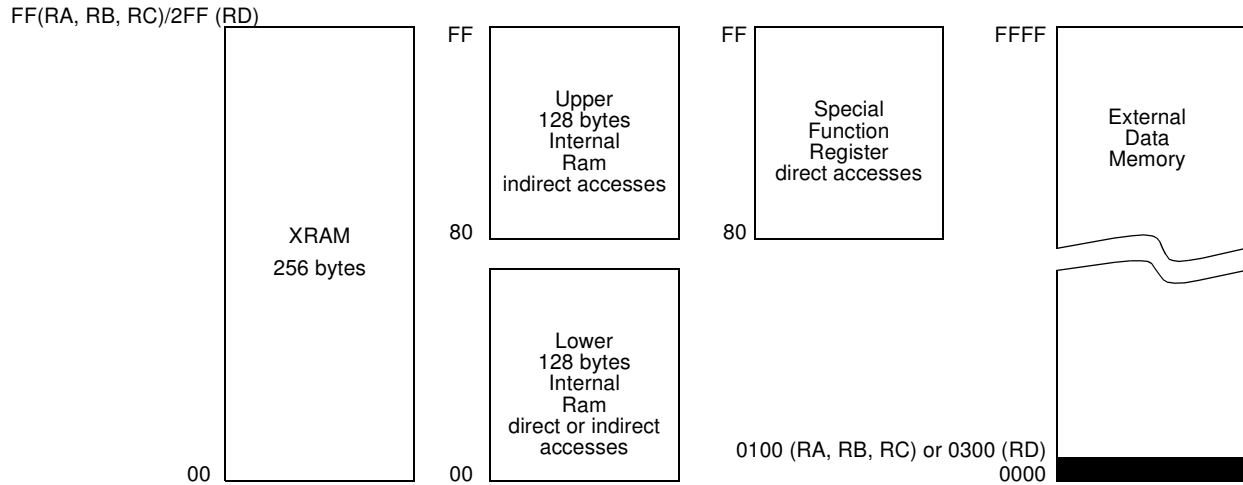


Table 6-1. Auxiliary Register AUXR

AUXR Address 08EH		-	-	-	-	-	-	EXTRAM	AO
Reset value		X	X	X	X	X	X	0	0
Symbol	Function								
-	Not implemented, reserved for future use. ⁽¹⁾								
AO	Disable/Enable ALE								
	AO	Operating Mode							
	0	ALE is emitted at a constant rate of 1/6 the oscillator frequency (or 1/3 if X2 mode is used)							
	1	ALE is active only during a MOVX or MOVC instruction							
EXTRAM	Internal/External RAM (00H-FFH) access using MOVX @ Ri/ @ DPTR								
	EXTRAM	Operating Mode							
	0	Internal XRAM access using MOVX @ Ri/ @ DPTR							
	1	External data memory access							

1. User software should not write 1s to reserved bits. These bits may be used in future 8051 family products to invoke new features. In that case, the reset or inactive value of the new bit will be 0, and its active value will be 1. The value read from a reserved bit is indeterminate.

6.2 Timer 2

The timer 2 in the TS80C51RX2 is compatible with the timer 2 in the 80C52.

It is a 16-bit timer/counter: the count is maintained by two eight-bit timer registers, TH2 and TL2, connected in cascade. It is controlled by T2CON register (See Table 6-2) and T2MOD register (See Table 6-3). Timer 2 operation is similar to Timer 0 and Timer 1. $\overline{C/T2}$ selects $F_{OSC}/12$ (timer operation) or external pin T2 (counter operation) as the timer clock input. Setting TR2 allows TL2 to be incremented by the selected input.

Timer 2 has 3 operating modes: capture, autoreload and Baud Rate Generator. These modes are selected by the combination of RCLK, TCLK and $\overline{CP/RL2}$ (T2CON), as described in the Atmel 8-bit Microcontroller Hardware description.

Refer to the Atmel 8-bit Microcontroller Hardware description for the description of Capture and Baud Rate Generator Modes.

In TS80C51RX2 Timer 2 includes the following enhancements:

- Auto-reload mode with up or down counter
- Programmable clock-output

6.2.1 Auto-reload Mode

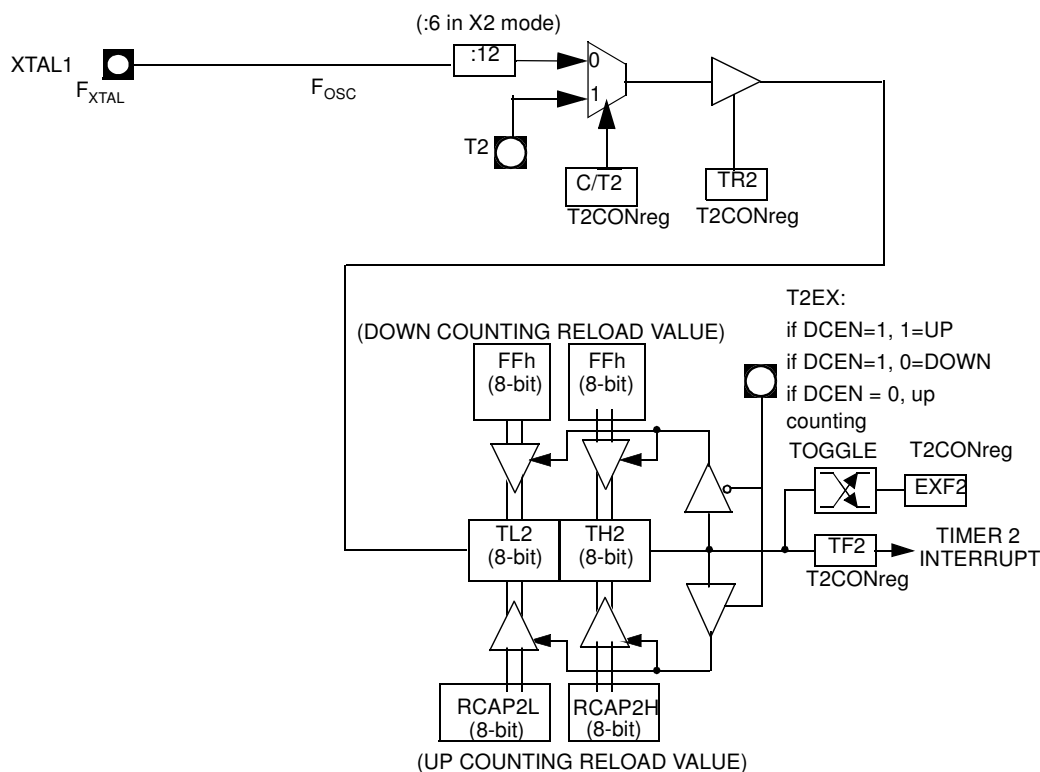
The auto-reload mode configures timer 2 as a 16-bit timer or event counter with automatic reload. If DCEN bit in T2MOD is cleared, timer 2 behaves as in 80C52 (refer to the Atmel 8-bit Microcontroller Hardware description). If DCEN bit is set, timer 2 acts as an Up/down timer/counter as shown in Figure 6-2. In this mode the T2EX pin controls the direction of count.

When T2EX is high, timer 2 counts up. Timer overflow occurs at FFFFh which sets the TF2 flag and generates an interrupt request. The overflow also causes the 16-bit value in RCAP2H and RCAP2L registers to be loaded into the timer registers TH2 and TL2.

When T2EX is low, timer 2 counts down. Timer underflow occurs when the count in the timer registers TH2 and TL2 equals the value stored in RCAP2H and RCAP2L registers. The underflow sets TF2 flag and reloads FFFFh into the timer registers.

The EXF2 bit toggles when timer 2 overflows or underflows according to the the direction of the count. EXF2 does not generate any interrupt. This bit can be used to provide 17-bit resolution.

Figure 6-2. Auto-reload Mode Up/Down Counter (DCEN = 1)



6.2.2 Programmable Clock-Output

In the clock-out mode, timer 2 operates as a 50%-duty-cycle, programmable clock generator (See Figure 6-3). The input clock increments TL2 at frequency $F_{OSC}/2$. The timer repeatedly counts to overflow from a loaded value. At overflow, the contents of RCAP2H and RCAP2L registers are loaded into TH2 and TL2. In this mode, timer 2 overflows do not generate interrupts. The formula gives the clock-out frequency as a function of the system oscillator frequency and the value in the RCAP2H and RCAP2L registers:

$$Clock - OutFrequency = \frac{F_{osc}}{4 \times (65536 - RCAP2H/RCAP2L)}$$

For a 16 MHz system clock, timer 2 has a programmable frequency range of 61 Hz ($F_{OSC}/2^{16}$) to 4 MHz ($F_{OSC}/4$). The generated clock signal is brought out to T2 pin (P1.0).

Timer 2 is programmed for the clock-out mode as follows:

- Set T2OE bit in T2MOD register.
- Clear $\overline{C/T2}$ bit in T2CON register.
- Determine the 16-bit reload value from the formula and enter it in RCAP2H/RCAP2L registers.
- Enter a 16-bit initial value in timer registers TH2/TL2. It can be the same as the reload value or a different one depending on the application.
- To start the timer, set TR2 run control bit in T2CON register.

Bit Number	Bit Mnemonic	Description
7	TF2	Timer 2 overflow Flag Must be cleared by software. Set by hardware on timer 2 overflow, if RCLK = 0 and TCLK = 0.
6	EXF2	Timer 2 External Flag Set when a capture or a reload is caused by a negative transition on T2EX pin if EXEN2=1. When set, causes the CPU to vector to timer 2 interrupt routine when timer 2 interrupt is enabled. Must be cleared by software. EXF2 doesn't cause an interrupt in Up/down counter mode (DCEN = 1)
5	RCLK	Receive Clock bit Clear to use timer 1 overflow as receive clock for serial port in mode 1 or 3. Set to use timer 2 overflow as receive clock for serial port in mode 1 or 3.
4	TCLK	Transmit Clock bit Clear to use timer 1 overflow as transmit clock for serial port in mode 1 or 3. Set to use timer 2 overflow as transmit clock for serial port in mode 1 or 3.
3	EXEN2	Timer 2 External Enable bit Clear to ignore events on T2EX pin for timer 2 operation. Set to cause a capture or reload when a negative transition on T2EX pin is detected, if timer 2 is not used to clock the serial port.
2	TR2	Timer 2 Run control bit Clear to turn off timer 2. Set to turn on timer 2.
1	C/T2#	Timer/Counter 2 select bit Clear for timer operation (input from internal clock system: F _{OSC}). Set for counter operation (input from T2 input pin, falling edge trigger). Must be 0 for clock out mode.
0	CP/RL2#	Timer 2 Capture/Reload bit If RCLK=1 or TCLK=1, CP/RL2# is ignored and timer is forced to auto-reload on timer 2 overflow. Clear to auto-reload on timer 2 overflows or negative transitions on T2EX pin if EXEN2=1. Set to capture on negative transitions on T2EX pin if EXEN2=1.

Reset Value = 0000 0000b

Bit addressable

Table 6-3. T2MOD Register
T2MOD - Timer 2 Mode Control Register (C9h)

7	6	5	4	3	2	1	0
-	-	-	-	-	-	T2OE	DCEN

6.4 TS80C51Rx2 Serial I/O Port

The serial I/O port in the TS80C51Rx2 is compatible with the serial I/O port in the 80C52.

It provides both synchronous and asynchronous communication modes. It operates as an Universal Asynchronous Receiver and Transmitter (UART) in three full-duplex modes (Modes 1, 2 and 3). Asynchronous transmission and reception can occur simultaneously and at different baud rates

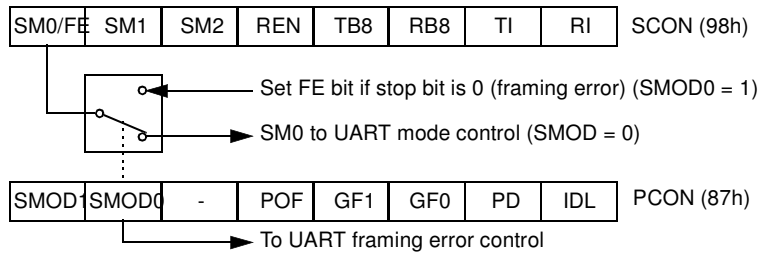
Serial I/O port includes the following enhancements:

- Framing error detection
- Automatic address recognition

6.4.1 Framing Error Detection

Framing bit error detection is provided for the three asynchronous modes (modes 1, 2 and 3). To enable the framing bit error detection feature, set SMOD0 bit in PCON register (See Figure 6-10).

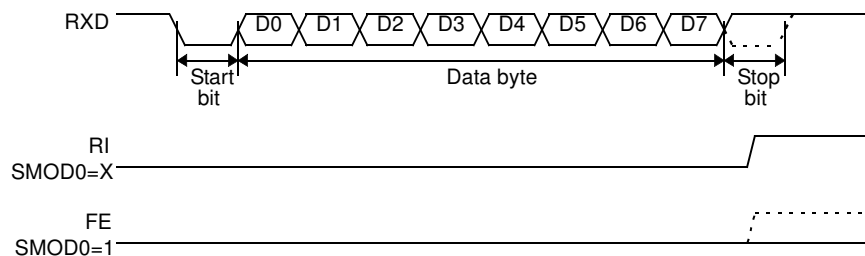
Figure 6-10. Framing Error Block Diagram



When this feature is enabled, the receiver checks each incoming data frame for a valid stop bit. An invalid stop bit may result from noise on the serial lines or from simultaneous transmission by two CPUs. If a valid stop bit is not found, the Framing Error bit (FE) in SCON register (See Table 6-14.) bit is set.

Software may examine FE bit after each reception to check for data errors. Once set, only software or a reset can clear FE bit. Subsequently received frames with valid stop bits cannot clear FE bit. When FE feature is enabled, RI rises on stop bit instead of the last data bit (See Figure 6-11 and Figure 6-12).

Figure 6-11. UART Timings in Mode 1



Bit Number	Bit Mnemonic	Description
7	SMOD1	Serial port Mode bit 1 Set to select double baud rate in mode 1, 2 or 3.
6	SMOD0	Serial port Mode bit 0 Clear to select SM0 bit in SCON register. Set to to select FE bit in SCON register.
5	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
4	POF	Power-Off Flag Clear to recognize next reset type. Set by hardware when VCC rises from 0 to its nominal voltage. Can also be set by software.
3	GF1	General purpose Flag Cleared by user for general purpose usage. Set by user for general purpose usage.
2	GF0	General purpose Flag Cleared by user for general purpose usage. Set by user for general purpose usage.
1	PD	Power-Down mode bit Cleared by hardware when reset occurs. Set to enter power-down mode.
0	IDL	Idle mode bit Clear by hardware when interrupt or reset occurs. Set to enter idle mode.

Reset Value = 00X1 0000b

Not bit addressable

Power-off flag reset value will be 1 only after a power on (cold reset). A warm reset doesn't affect the value of this bit.

Table 6-16. Priority Level Bit Values

IPH.x	IP.x	Interrupt Level Priority
0	0	0 (Lowest)
0	1	1
1	0	2
1	1	3 (Highest)

A low-priority interrupt can be interrupted by a high priority interrupt, but not by another low-priority interrupt. A high-priority interrupt can't be interrupted by any other interrupt source.

If two interrupt requests of different priority levels are received simultaneously, the request of higher priority level is serviced. If interrupt requests of the same priority level are received simultaneously, an internal polling sequence determines which request is serviced. Thus within each priority level there is a second priority structure determined by the polling sequence.

Table 6-17. IE Register
IE - Interrupt Enable Register (A8h)

7	6	5	4	3	2	1	0
EA	EC	ET2	ES	ET1	EX1	ET0	EX0
Bit Number	Bit	Mnemonic	Description				
7	EA		Enable All interrupt bit Clear to disable all interrupts. Set to enable all interrupts. If EA=1, each interrupt source is individually enabled or disabled by setting or clearing its own interrupt enable bit.				
6	EC		PCA interrupt enable bit Clear to disable . Set to enable.				
5	ET2		Timer 2 overflow interrupt Enable bit Clear to disable timer 2 overflow interrupt. Set to enable timer 2 overflow interrupt.				
4	ES		Serial port Enable bit Clear to disable serial port interrupt. Set to enable serial port interrupt.				
3	ET1		Timer 1 overflow interrupt Enable bit Clear to disable timer 1 overflow interrupt. Set to enable timer 1 overflow interrupt.				
2	EX1		External interrupt 1 Enable bit Clear to disable external interrupt 1. Set to enable external interrupt 1.				
1	ET0		Timer 0 overflow interrupt Enable bit Clear to disable timer 0 overflow interrupt. Set to enable timer 0 overflow interrupt.				
0	EX0		External interrupt 0 Enable bit Clear to disable external interrupt 0. Set to enable external interrupt 0.				

Reset Value = 0000 0000b

Bit addressable

Table 6-18. IP Register
IP - Interrupt Priority Register (B8h)

7	6	5	4	3	2	1	0
-	PPC	PT2	PS	PT1	PX1	PT0	PX0
Bit Number	Bit Mnemonic	Description					
7	-	Reserved The value read from this bit is indeterminate. Do not set this bit.					
6	PPC	PCA interrupt priority bit Refer to PPCH for priority level.					
5	PT2	Timer 2 overflow interrupt Priority bit Refer to PT2H for priority level.					
4	PS	Serial port Priority bit Refer to PSH for priority level.					
3	PT1	Timer 1 overflow interrupt Priority bit Refer to PT1H for priority level.					
2	PX1	External interrupt 1 Priority bit Refer to PX1H for priority level.					
1	PT0	Timer 0 overflow interrupt Priority bit Refer to PT0H for priority level.					
0	PX0	External interrupt 0 Priority bit Refer to PX0H for priority level.					

Reset Value = X000 0000b
Bit addressable

11. Electrical Characteristics

11.1 Absolute Maximum Ratings

Ambient Temperature Under Bias: C = commercial.....0°C to 70°C I = industrial-40°C to 85°C Storage Temperature -65°C to + 150°C Voltage on V _{CC} to V _{SS}-0.5 V to + 7 V Voltage on Any Pin to V _{SS}-0.5 V to V _{CC} + 0.5 V Power Dissipation 1 W	*NOTICE: Stresses at or above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions may affect device reliability. Power dissipation is based on the maximum allowable die temperature and the thermal resistance of the package.
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11.2 Power Consumption Measurement

Since the introduction of the first C51 devices, every manufacturer made operating I_{CC} measurements under reset, which made sense for the designs where the CPU was running under reset. In Atmel new devices, the CPU is no more active during reset, so the power consumption is very low but is not really representative of what will happen in the customer system. That's why, while keeping measurements under Reset, Atmel presents a new way to measure the operating I_{CC}:

Using an internal test ROM, the following code is executed:

Label: SJMP Label (80 FE)

Ports 1, 2, 3 are disconnected, Port 0 is tied to FFh, EA = V_{CC}, RST = V_{SS}, XTAL2 is not connected and XTAL1 is driven by the clock.

This is much more representative of the real operating I_{CC}.

11.3 DC Parameters for Standard Voltage

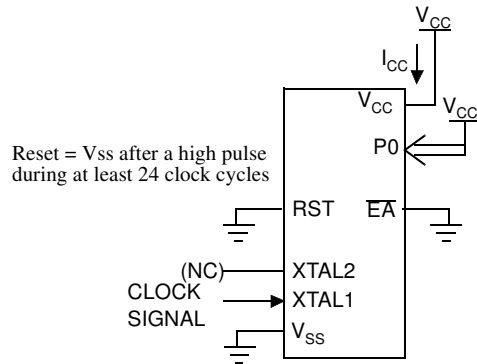
T_A = 0°C to +70°C; V_{SS} = 0 V; V_{CC} = 5 V ± 10%; F = 0 to 40 MHz.

T_A = -40°C to +85°C; V_{SS} = 0 V; V_{CC} = 5 V ± 10%; F = 0 to 40 MHz.

Table 11-1. DC Parameters in Standard Voltage

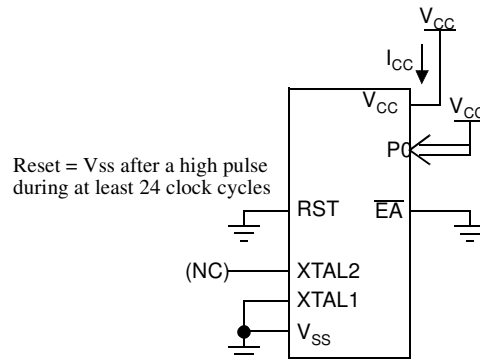
Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V _{IL}	Input Low Voltage	-0.5		0.2 V _{CC} - 0.1	V	
V _{IH}	Input High Voltage except XTAL1, RST	0.2 V _{CC} + 0.9		V _{CC} + 0.5	V	
V _{IH1}	Input High Voltage, XTAL1, RST	0.7 V _{CC}		V _{CC} + 0.5	V	
V _{OL}	Output Low Voltage, ports 1, 2, 3, 4, 5 ⁽⁶⁾			0.3	V	I _{OL} = 100 μA ⁽⁴⁾
				0.45	V	I _{OL} = 1.6 mA ⁽⁴⁾
				1.0	V	I _{OL} = 3.5 mA ⁽⁴⁾
V _{OL1}	Output Low Voltage, port 0 ⁽⁶⁾			0.3	V	I _{OL} = 200 μA ⁽⁴⁾
				0.45	V	I _{OL} = 3.2 mA ⁽⁴⁾
				1.0	V	I _{OL} = 7.0 mA ⁽⁴⁾
V _{OL2}	Output Low Voltage, ALE, $\overline{\text{PSEN}}$			0.3	V	I _{OL} = 100 μA ⁽⁴⁾
				0.45	V	I _{OL} = 1.6 mA ⁽⁴⁾
				1.0	V	I _{OL} = 3.5 mA ⁽⁴⁾

Figure 11-3. I_{CC} Test Condition, Idle Mode



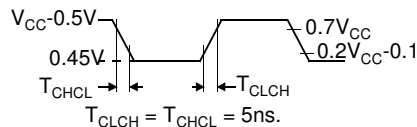
All other pins are disconnected.

Figure 11-4. I_{CC} Test Condition, Power-Down Mode



All other pins are disconnected.

Figure 11-5. Clock Signal Waveform for I_{CC} Tests in Active and Idle Modes



11.5 AC Parameters

11.5.1 Explanation of the AC Symbols

Each timing symbol has 5 characters. The first character is always a “T” (stands for time). The other characters, depending on their positions, stand for the name of a signal or the logical status of that signal. The following is a list of all the characters and what they stand for.

Example: T_{AVLL} = Time for Address Valid to ALE Low.

T_{LLPL} = Time for ALE Low to \overline{PSEN} Low.

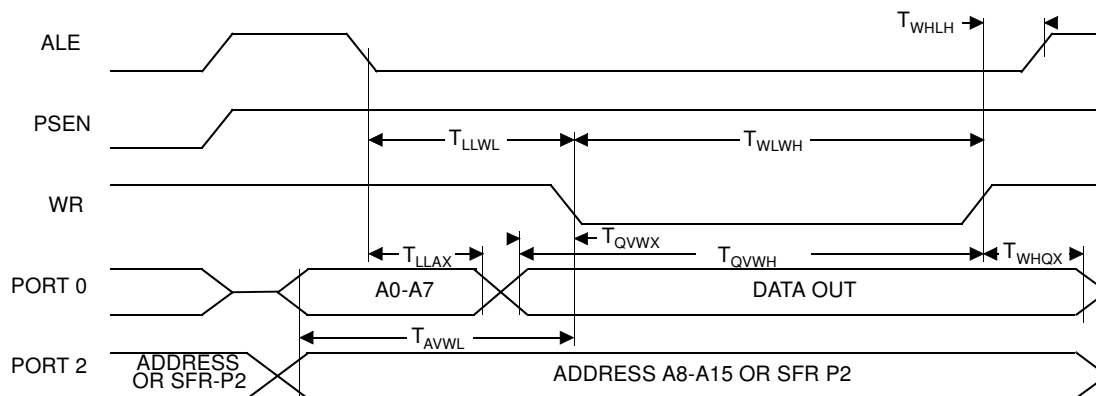
T_A = 0 to +70°C (commercial temperature range); V_{SS} = 0 V; V_{CC} = 5 V \pm 10%; -M and -V ranges.
 T_A = -40°C to +85°C (industrial temperature range); V_{SS} = 0 V; V_{CC} = 5 V \pm 10%; -M and -V ranges.

Table 11-9. AC Parameters for a Variable Clock: derating formula

Symbol	Type	Standard Clock	X2 Clock	-M	-V	-L	Units
T_{RLRH}	Min	6 T - x	3 T - x	20	15	25	ns
T_{WLWH}	Min	6 T - x	3 T - x	20	15	25	ns
T_{RLDV}	Max	5 T - x	2.5 T - x	25	23	30	ns
T_{RHDX}	Min	x	x	0	0	0	ns
T_{RHDZ}	Max	2 T - x	T - x	20	15	25	ns
T_{LLDV}	Max	8 T - x	4T - x	40	35	45	ns
T_{AVDV}	Max	9 T - x	4.5 T - x	60	50	65	ns
T_{LLWL}	Min	3 T - x	1.5 T - x	25	20	30	ns
T_{LLWL}	Max	3 T + x	1.5 T + x	25	20	30	ns
T_{AVWL}	Min	4 T - x	2 T - x	25	20	30	ns
T_{QVWX}	Min	T - x	0.5 T - x	15	10	20	ns
T_{QVWH}	Min	7 T - x	3.5 T - x	15	10	20	ns
T_{WHQX}	Min	T - x	0.5 T - x	10	8	15	ns
T_{RLAZ}	Max	x	x	0	0	0	ns
T_{WHLH}	Min	T - x	0.5 T - x	15	10	20	ns
T_{WHLH}	Max	T + x	0.5 T + x	15	10	20	ns

11.5.5 External Data Memory Write Cycle

Figure 11-7. External Data Memory Write Cycle

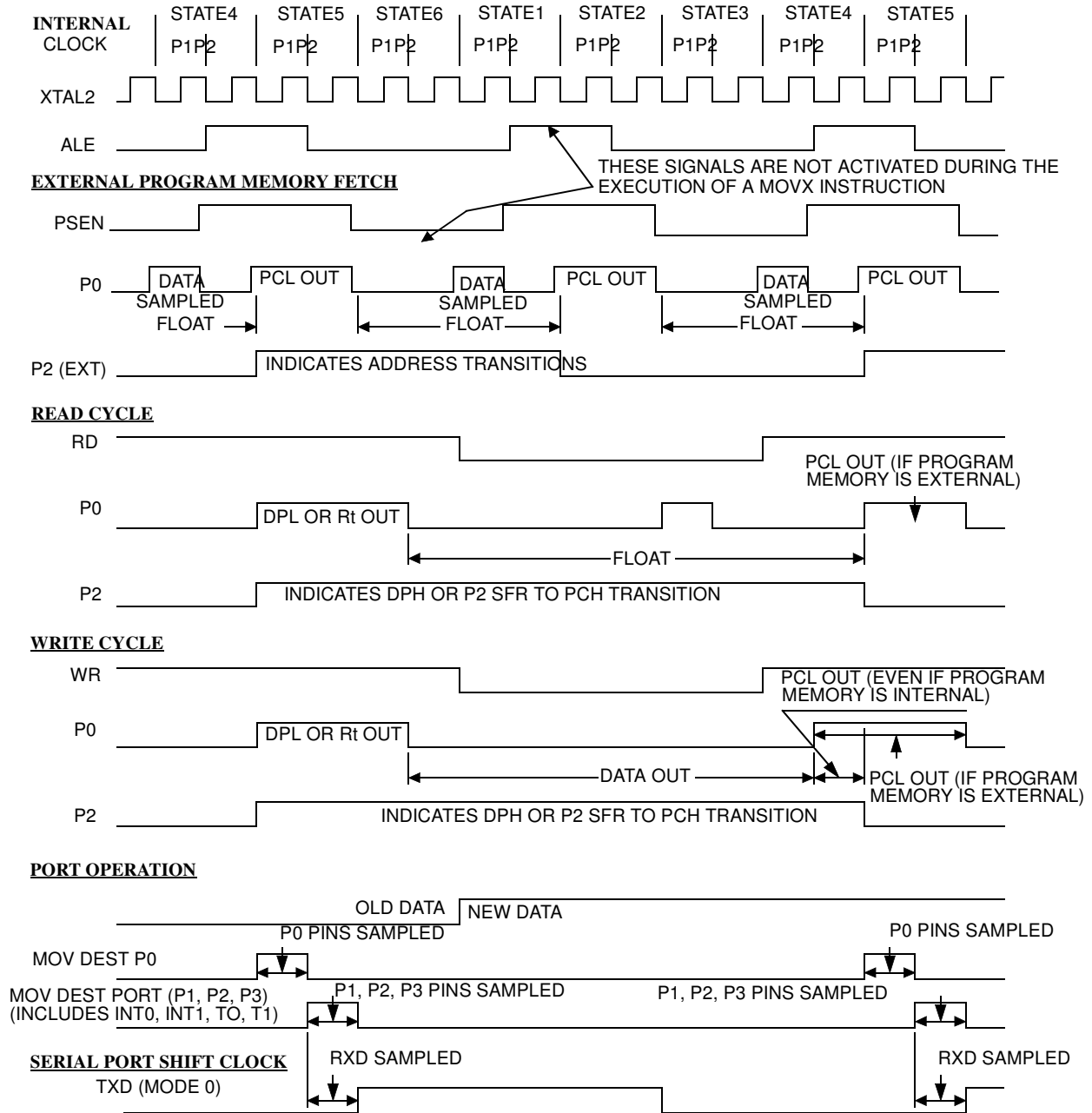


11.5.6 External Data Memory Read Cycle

11.5.15 Clock Waveforms

Valid in normal clock mode. In X2 mode XTAL2 signal must be changed to XTAL2 divided by two.

Figure 11-14. Clock Waveforms



This diagram indicates when signals are clocked internally. The time it takes the signals to propagate to the pins, however, ranges from 25 to 125 ns. This propagation delay is dependent on variables such as temperature and pin loading. Propagation also varies from output to output and component. Typically though ($T_A=25^\circ\text{C}$ fully loaded) RD and WR propagation delays are approximately 50ns. The other signals are typically 85 ns. Propagation delays are incorporated in the AC specifications.

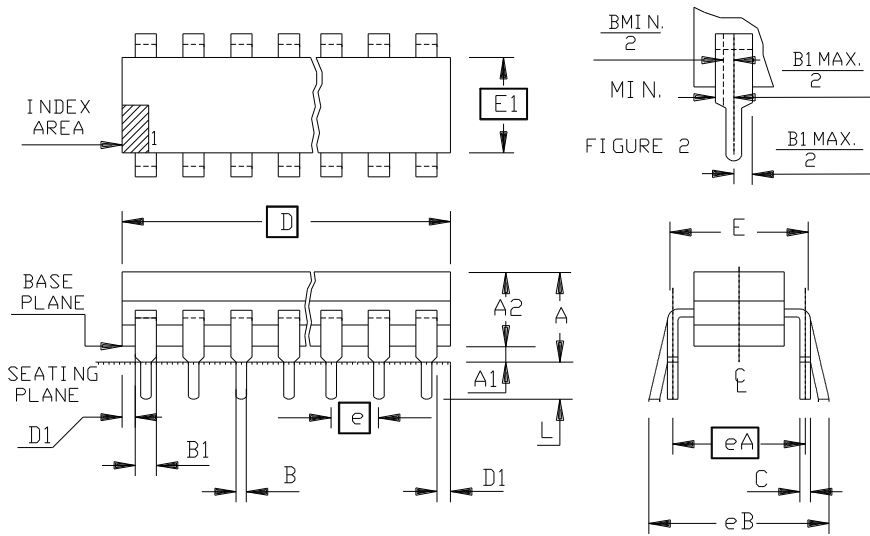
Part Number	Memory size	Supply Voltage	Temperature Range	Max Frequency	Package	Packing
TS87C51RB2-MCA						
TS87C51RB2-MCB						
TS87C51RB2-MCE						
TS87C51RB2-MIA						
TS87C51RB2-MIB						
TS87C51RB2-MIE						
TS87C51RB2-LCA						
TS87C51RB2-LCB						
TS87C51RB2-LCE						
TS87C51RB2-LIA						
TS87C51RB2-LIB						
TS87C51RB2-LIE						
TS87C51RB2-VCA						
TS87C51RB2-VCB						
TS87C51RB2-VCE						
TS87C51RB2-VIA						
TS87C51RB2-VIB						
TS87C51RB2-VIE						
OBSOLETE						
AT87C51RB2-3CSUM	OTP 16k Bytes	5V	Industrial & Green	40 MHz (20 MHz X2)	PDIL40	Stick
AT87C51RB2-SLSUM	OTP 16k Bytes	5V	Industrial & Green	40 MHz (20 MHz X2)	PLCC44	Stick
AT87C51RB2-RLTUM	OTP 16k Bytes	5V	Industrial & Green	40 MHz (20 MHz X2)	VQFP44	Tray
AT87C51RB2-3CSUL	OTP 16k Bytes	3-5V	Industrial & Green	30 MHz (20 MHz X2)	PDIL40	Stick
AT87C51RB2-SLSUL	OTP 16k Bytes	3-5V	Industrial & Green	30 MHz (20 MHz X2)	PLCC44	Stick
AT87C51RB2-RLTUL	OTP 16k Bytes	3-5V	Industrial & Green	30 MHz (20 MHz X2)	VQFP44	Tray



Part Number	Memory size	Supply Voltage	Temperature Range	Max Frequency	Package	Packing
TS87C51RD2-MCA						
TS87C51RD2-MCB						
TS87C51RD2-MCE						
TS87C51RD2-MIA						
TS87C51RD2-MIB						
TS87C51RD2-MIE						
TS87C51RD2-LCA						
TS87C51RD2-LCB						
TS87C51RD2-LCE						
TS87C51RD2-LIA						
TS87C51RD2-LIB						
TS87C51RD2-LIE						
TS87C51RD2-VCA						
TS87C51RD2-VCB						
TS87C51RD2-VCE						
TS87C51RD2-VCL						
TS87C51RD2-VIA						
TS87C51RD2-VIB						
TS87C51RD2-VIE						
OBSOLETE						
AT87C51RD2-3CSUM	OTP 64k Bytes	5V	Industrial & Green	40 MHz (20 MHz X2)	PDIL40	Stick
AT87C51RD2-SLSUM	OTP 64k Bytes	5V	Industrial & Green	40 MHz (20 MHz X2)	PLCC44	Stick
AT87C51RD2-RLTUM	OTP 64k Bytes	5V	Industrial & Green	40 MHz (20 MHz X2)	VQFP44	Tray
AT87C51RD2-3CSUL	OTP 64k Bytes	3-5V	Industrial & Green	30 MHz (20 MHz X2)	PDIL40	Stick
AT87C51RD2-SLSUL	OTP 64k Bytes	3-5V	Industrial & Green	30 MHz (20 MHz X2)	PLCC44	Stick
AT87C51RD2-RLTUL	OTP 64k Bytes	3-5V	Industrial & Green	30 MHz (20 MHz X2)	VQFP44	Tray



13.2 PDIL40



	MM		INCH	
A	-	5.08	-	.200
A1	0.38	-	.015	-
A2	3.18	4.95	.125	.195
B	0.36	0.56	.014	.022
B1	0.76	1.78	.030	.070
C	0.20	0.38	.008	.015
D	50.29	53.21	1.980	2.095
E	15.24	15.87	.600	.625
E1	12.32	14.73	.485	.580
e	2.54	B. S. C	.100	B. S. C
eA	15.24	B. S. C	.600	B. S. C
eB	-	17.78	-	.700
L	2.93	3.81	.115	.150
D1	0.13	-	.005	-
PKG STD	02			